

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

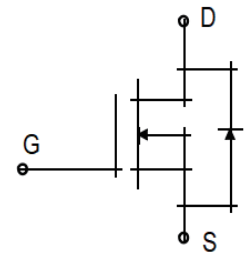
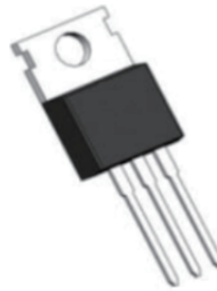
Product Summary

BVDSS	R _{DS(on)}	I _D
150V	9.5mΩ	120A

Description

The 120N15T is the high cell density trenched N-ch MOSFETs, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications.

The 120N15T meet the RoHS and Green Product, requirement 100% EAS guaranteed with full function reliability approved.

TO-220 Pin Configuration

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-Source Voltage	150	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Continuous Drain Current	T _C =25°C	120
		T _C =100°C	56
I _{DM}	Pulsed Drain Current ¹	352	A
EAS	Single Pulse Avalanche Energy ²	204.8	mJ
P _D	Total Power Dissipation	T _C =25°C 178.6	W
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	52	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	0.7	°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit		
Static Characteristics								
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	150	-	-	V		
I_{GSS}	Gate-body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA		
I_{DSS}	Zero Gate Voltage Drain Current	$T_J = 25^\circ\text{C}$	-	-	1	μA		
		$T_J = 100^\circ\text{C}$	-	-	100			
$V_{GS(th)}$	Gate-Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V		
$R_{DS(on)}$	Drain-Source On-Resistance ⁴	$V_{GS} = 10V, I_D = 20A$	-	9.5	11.5	m Ω		
g_{fs}	Forward Transconductance ⁴	$V_{DS} = 10V, I_D = 20A$	-	69	-	S		
Dynamic Characteristics ⁵								
C_{iss}	Input Capacitance	$V_{DS} = 75V, V_{GS} = 0V, f = 1\text{MHz}$	-	3310	-	μF		
C_{oss}	Output Capacitance		-	268	-			
C_{rss}	Reverse Transfer Capacitance		-	9.4	-			
R_g	Gate Resistance	$f = 1\text{MHz}$	-	3.2	-	Ω		
Switching Characteristics ⁵								
Q_g	Total Gate Charge	$V_{GS} = 10V, V_{DS} = 75V, I_D = 20A$	-	45	-	nC		
Q_{gs}	Gate-Source Charge		-	15	-			
Q_{gd}	Gate-Drain Charge		-	8.5	-			
$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = 10V, V_{DD} = 75V, R_G = 3\Omega, I_D = 20A$	-	16	-	ns		
t_r	Rise Time		-	12	-			
$t_{d(off)}$	Turn-Off Delay Time		-	30	-			
t_f	Fall Time		-	18	-			
t_{rr}	Body Diode Reverse Recovery Time		-	76	-			
Q_{rr}	Body Diode Reverse Recovery Charge		$I_F = 20A, dI/dt = 100A/\mu s$	-	182		-	nC
Drain-Source Body Diode Characteristics								
V_{SD}	Diode Forward Voltage ⁴	$I_S = 20A, V_{GS} = 0V$	-	-	1.2	V		
I_S	Continuous Source	$T_C = 25^\circ\text{C}$	-	-	120	A		

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_J(\text{MAX}) = 150^\circ\text{C}$
2. The EAS data shows Max. rating. The test condition is $V_{DD} = 50V, V_{GS} = 10V, L = 0.4\text{mH}, I_{AS} = 32A$.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Performance Characteristics

Figure 1: Output Characteristics

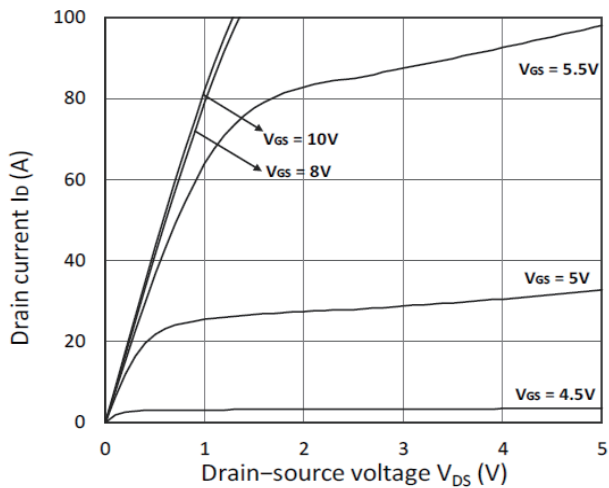


Figure 2: Typical Transfer Characteristics

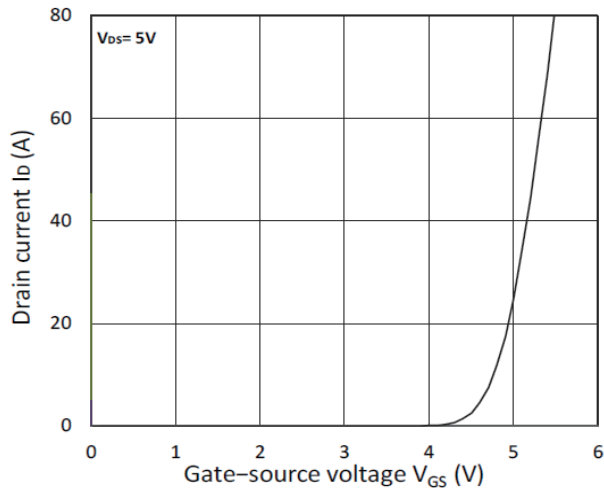


Figure 3: Forward Characteristics of Reverse

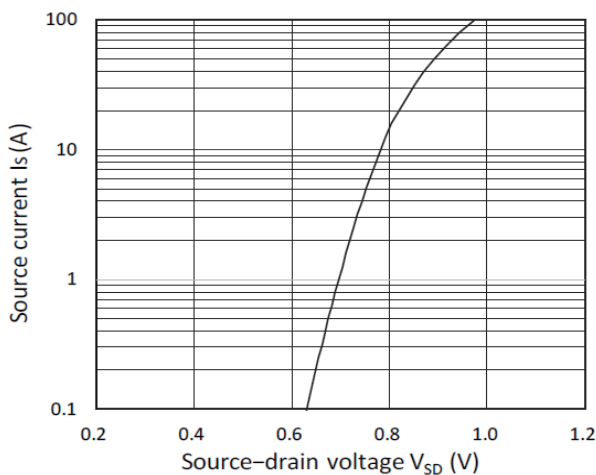


Figure 4: RDS(ON) vs. VGS

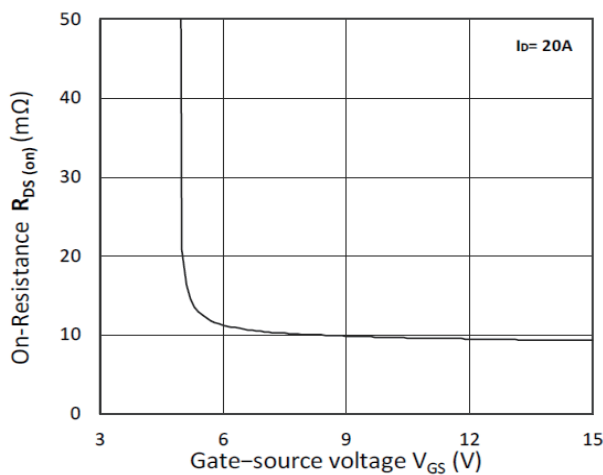


Figure 5: RDS(ON) vs. ID

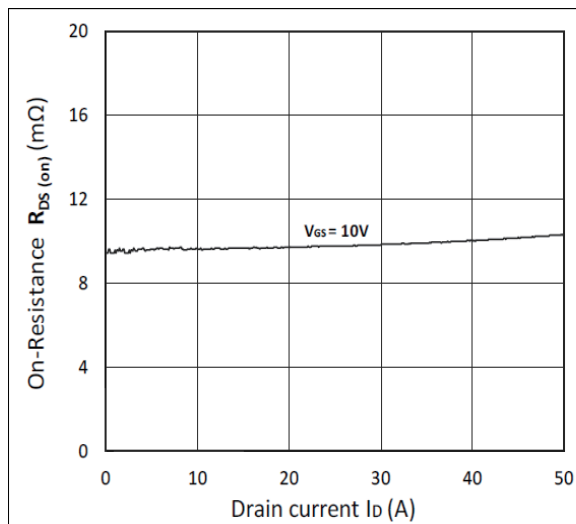
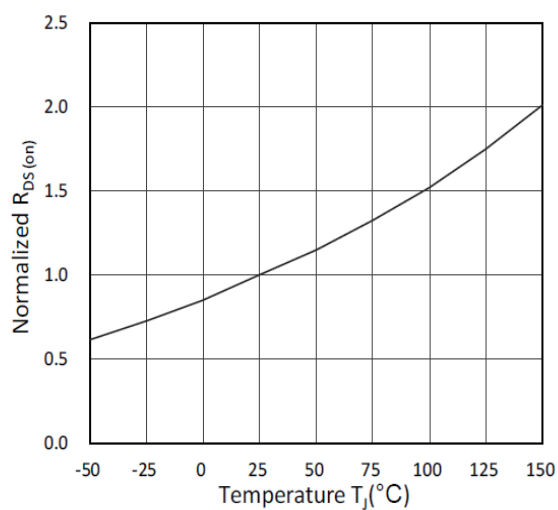


Figure 6: Normalized RDS(on) vs. Temperature



Typical Performance Characteristics

Figure 7: Capacitance Characteristics

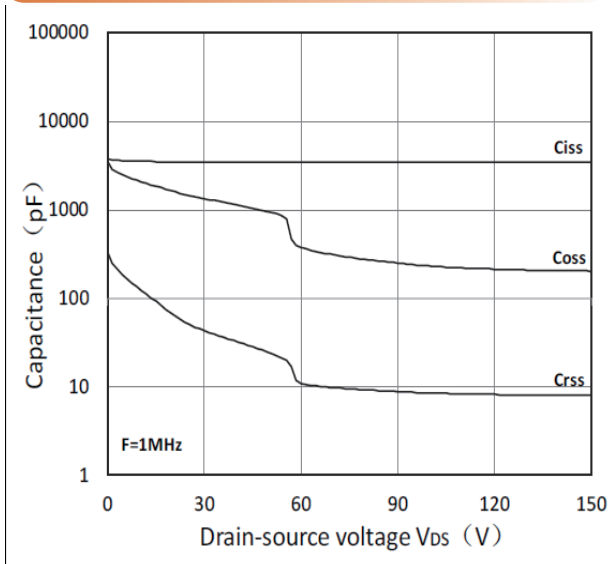


Figure 8: Gate Charge Characteristics

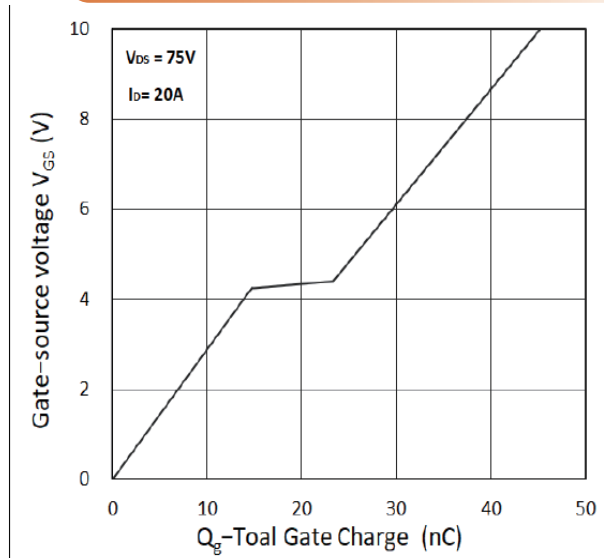


Figure 9: Power Dissipation

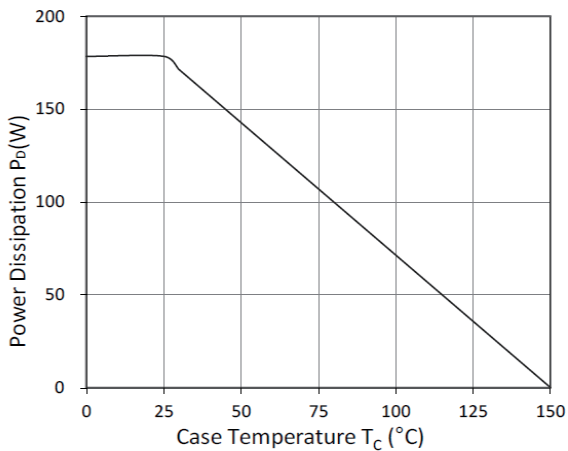


Figure 10: Safe Operating Area

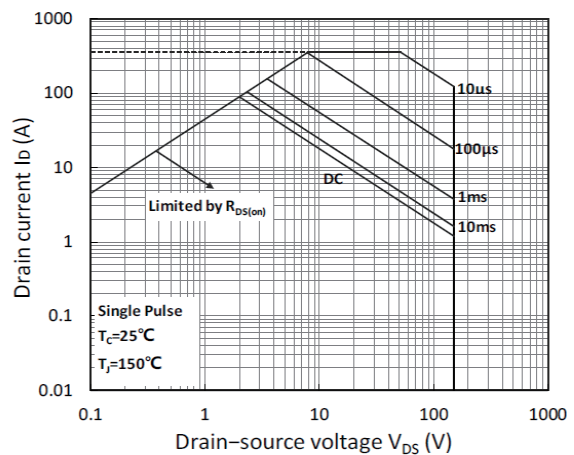
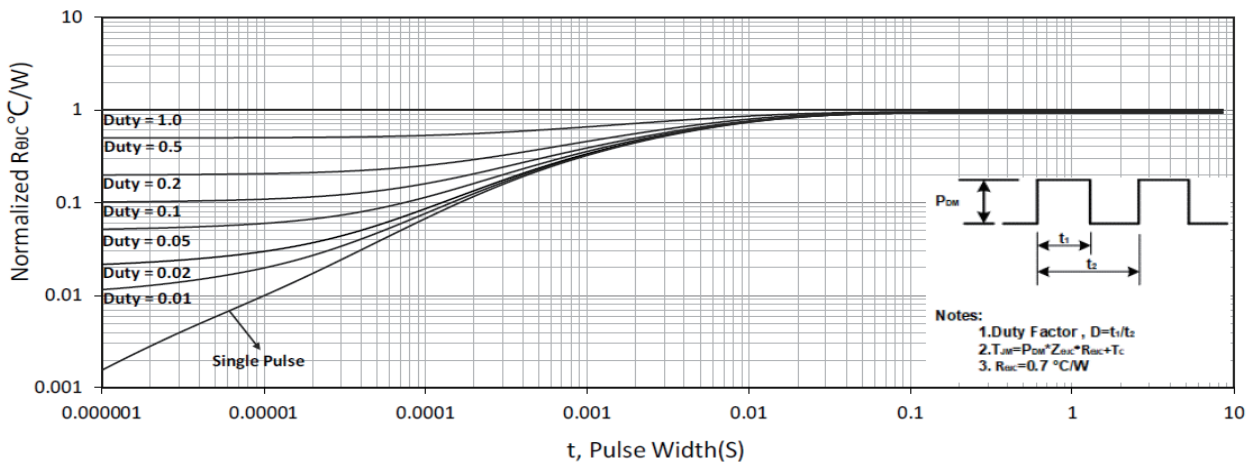


Figure 11: Normalized Maximum Transient Thermal Impedance



Test Circuit

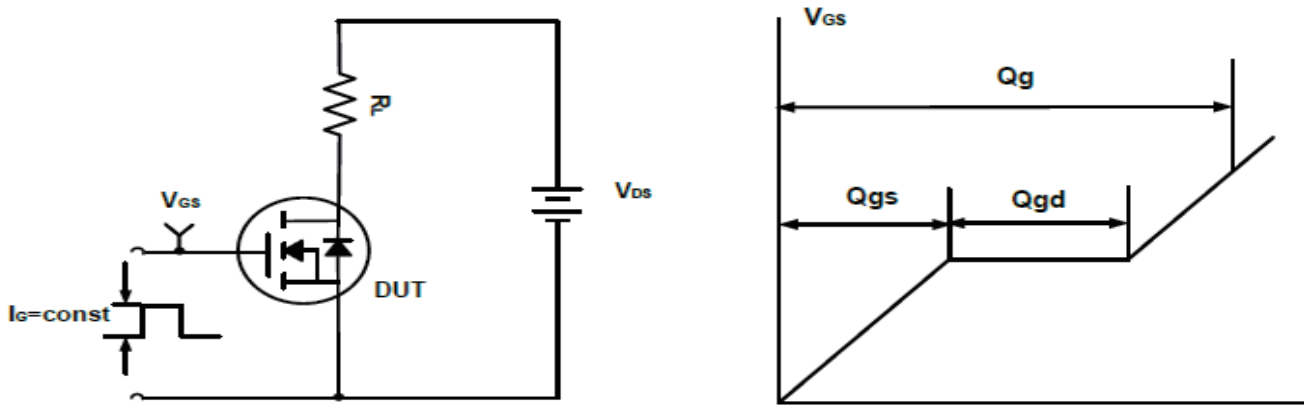


Figure A. Gate Charge Test Circuit & Waveforms

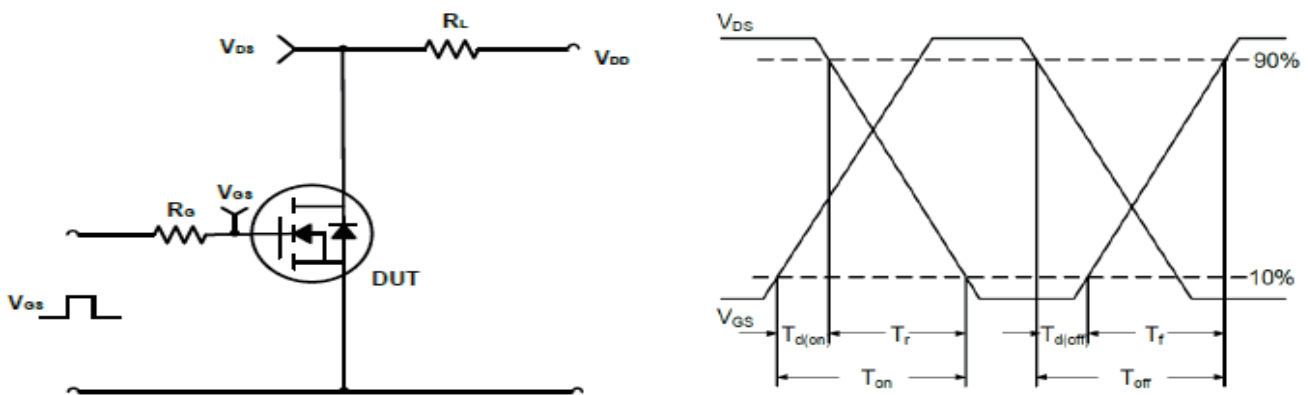


Figure B. Switching Test Circuit & Waveforms

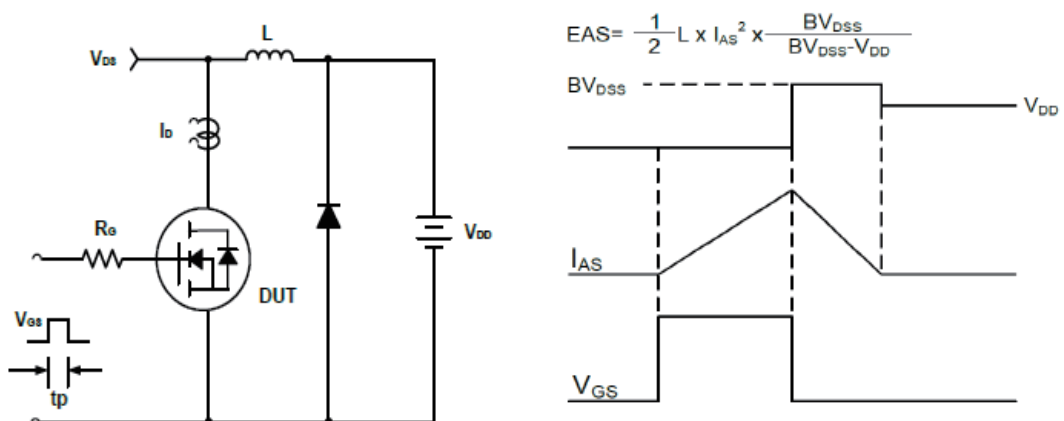
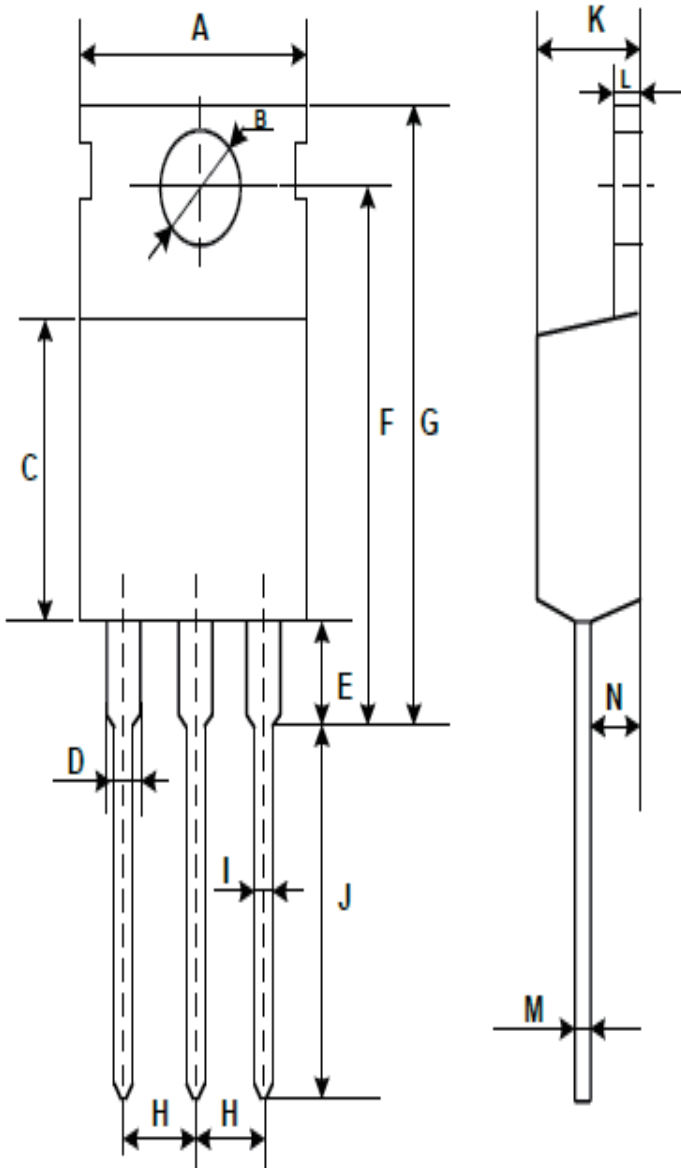


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Mechanical Dimensions for TO-220



COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	9.7	10.3
B	3.4	3.8
C	8.8	9.4
D	1.17	1.47
E	2.6	3.5
F	15.1	16.7
G	19.55MAX	
H	2.54REF	
I	0.7	0.95
J	9.35	11
K	4.3	4.77
L	1.2	1.45
M	0.4	0.65
N	2.2	2.6

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